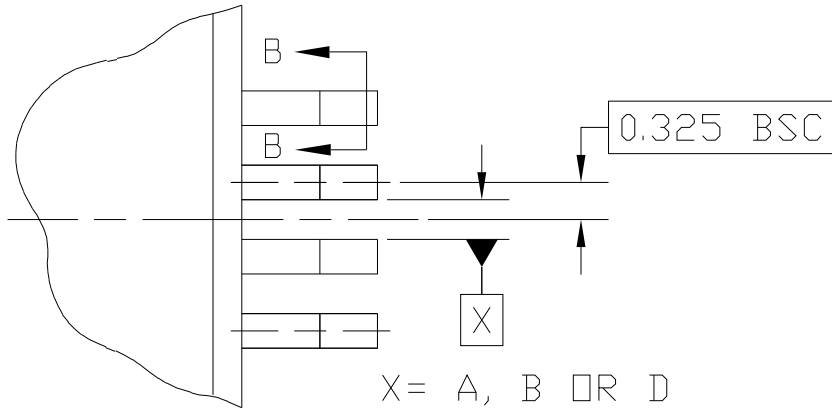
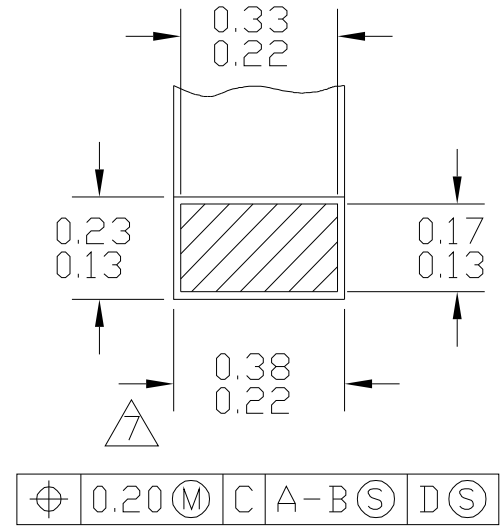


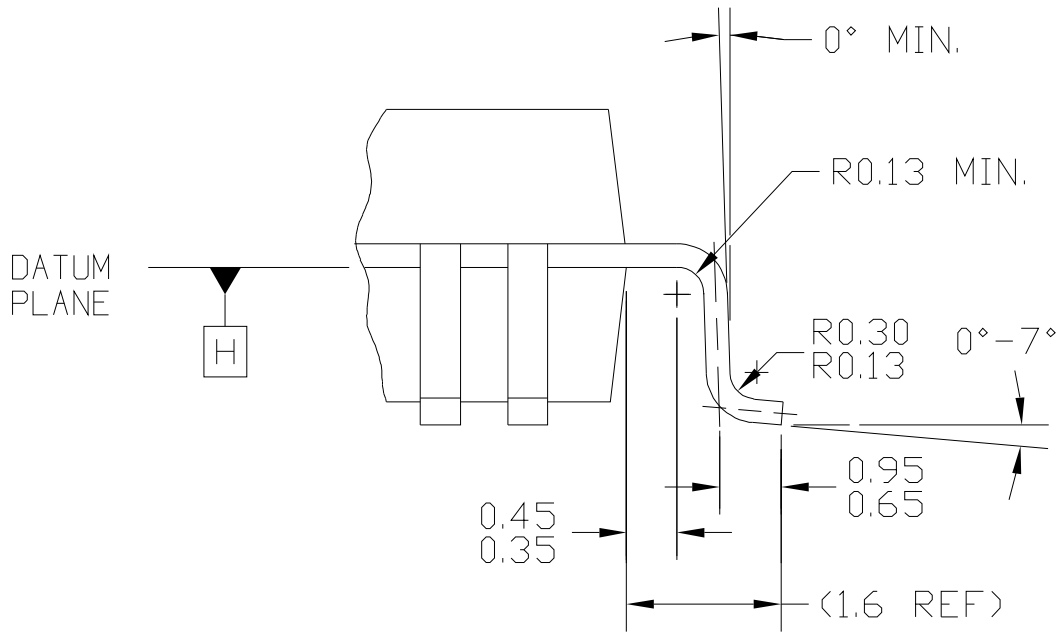
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TITLE: QUAD FLAT PACKAGE, 80 LEAD, 14 X 14 X 2.2 PKG, 0.65 LEAD PITCH	DOCUMENT NO: 98ASB42846B	REV: D
	STANDARD: NON-JEDEC	
	SOT1103-3	19 JAN 2016



DETAIL "A"



SECTION B-B
VIEW ROTATED 90°



DETAIL "C"

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		STANDARD: NON-JEDEC	
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NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS A-B AND -D- TO BE DETERMINED AT DATUM PLANE -H-.

5. DIMENSIONS TO BE DETERMINED AT SEATING PLANE -C-.

6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.

7. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF THE DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.

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